PRODUCT NO.

94898

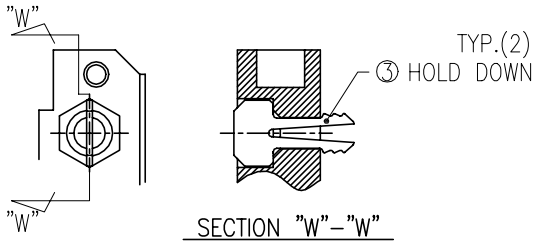
PRODUCT NO. 94898-XXXX	STAND OFF DIM"M"(mm)	SOLDER TAIL	DIM "P" (mm)	DIM "Q" (mm)	FOR LOWER DECK OR UPPER DECK	③ HOLD DOWN	SHEET NO.	MOUNTIMG STYLE TO PCB
000	0	R/A	2.8	—	LOWER	NONE	NO.2	TOP MOUNT 94898-0XXX
000LF	0	R/A	2.8	—	LOWER	NONE		
000MLF	0	R/A	2.8	—	LOWER	NONE		
000H	0	R/A	2.8	—	LOWER	YES		
000HLF	0	R/A	2.8	—	LOWER	YES		
001	0	SMT STAGGERED	—	—	LOWER	NONE		
001LF	0	SMT STAGGERED	—	—	LOWER	NONE		
001H	0	SMT STAGGERED	—	—	LOWER	YES		
001HLF	0	SMT STAGGERED	—	—	LOWER	YES		
002	0	SMT IN LINE	—	—	LOWER	NONE		
002LF	0	SMT IN LINE	—	—	LOWER	NONE		
002H	0	SMT IN LINE	—	—	LOWER	YES		
002HLF	0	SMT IN LINE	—	—	LOWER	YES		
010	4	R/A	2.8	—	LOWER	NONE	NO.3	BLACK COLOR
010LF	4	R/A	2.8	—	LOWER	NONE		
020	5	R/A	2.8	—	LOWER	NONE		
020LF	5	R/A	2.8	—	LOWER	NONE		
020MLF	5	R/A	2.8	—	LOWER	NONE		
021MLF	5	R/A	2.8	—	LOWER	NONE		
040	2	R/A	2.5	—	LOWER	NONE		
040MLF	2	R/A	2.5		LOWER	NONE		
040LF	2	R/A	2.5	—	LOWER	NONE		
005	FOR 0	R/A	2.8	8.6	UPPER	NONE	NO.4	
005LF	FOR 0	R/A	2.8	8.6	UPPER	NONE		
045	FOR 2	R/A	2.5	10.3	UPPER	NONE		
045MLF	FOR 2	R/A	2.5	10.3	UPPER	NONE		
045LF	FOR 2	R/A	2.5	10.3	UPPER	NONE		
500	0	R/A	2.8	—	LOWER	NONE	NO.5	BOTTOM MOUNT 94898-5XXX
500LF	0	R/A	2.8	—	LOWER	NONE		
500H	0	R/A	2.8	—	LOWER	YES		
500HLF	0	R/A	2.8	—	LOWER	YES		
501	0	SMT STAGGERED	—	—	LOWER	NONE		
501LF	0	SMT STAGGERED	—	—	LOWER	NONE		
501H	0	SMT STAGGERED	—	—	LOWER	YES		
501HLF	0	SMT STAGGERED	—	—	LOWER	YES		
502	0	SMT IN LINE	—	—	LOWER	NONE		
502J	0	SMT IN LINE	—	—	LOWER	NONE		
502LF	0	SMT IN LINE	—	—	LOWER	NONE		
502H	0	SMT IN LINE	—	—	LOWER	YES		
502HLF	0	SMT IN LINE	—	—	LOWER	YES		
510	4	R/A	2.8	—	LOWER	NONE	NO.6	NATURAL(WHITE)COLOR
510LF	4	R/A	2.8	—	LOWER	NONE		
520	5	R/A	2.8	—	LOWER	NONE		
520LF	5	R/A	2.8	—	LOWER	NONE		
530	2	R/A	1.48	—	LOWER	NONE		
530LF	2	R/A	1.48	—	LOWER	NONE		
540	2	R/A	2.5	—	LOWER	NONE		
540LF	2	R/A	2.5	—	LOWER	NONE		
505	FOR 0	R/A	2.8	8.6	UPPER	NONE	NO.7	
505LF	FOR 0	R/A	2.8	8.6	UPPER	NONE		
535	FOR 2	R/A	1.48	9.28	UPPER	NONE		
535LF	FOR 2	R/A	1.48	9.28	UPPER	NONE		
545	FOR 2	R/A	2.5	10.3	UPPER	NONE		
545LF	FOR 2	R/A	2.5	10.3	UPPER	NONE		

NOTES

1. PRODUCT SPEC:110-263

94898-X X X X X X

- OPTIONAL LEED FREE — NONE : NO
  LF : YES
- OPTIONAL HOLD DOWN — NONE : NO
  H : YES (SEE FIGURE OF -xxxH)
- LOW COST VERSION — NONE : NO
  M : YES (DETAIL AS COMPONENT)
- SOLDER TAIL — 0 : R/A (FOR LOWER & SINGLE)
  1 : SMT STAGGERED (FOR LOWER ONLY)
  2 : SMT IN LINE (FOR LOWER ONLY)
  5 : R/A (FOR UPPER ONLY)
- STAND OFF — 0 : 0mm
  1 : 4mm
  2 : 5mm
  3 : 2mm (SPECIAL TAIL LENGTH)
  4 : 2mm
- MOUNTING STYLE — 0 : TOP MOUNTING
  5 : BOTTOM MOUNTING



SECTION "W"-"W"

94898-xxxH
(OPTIONAL HOLD DOWN)

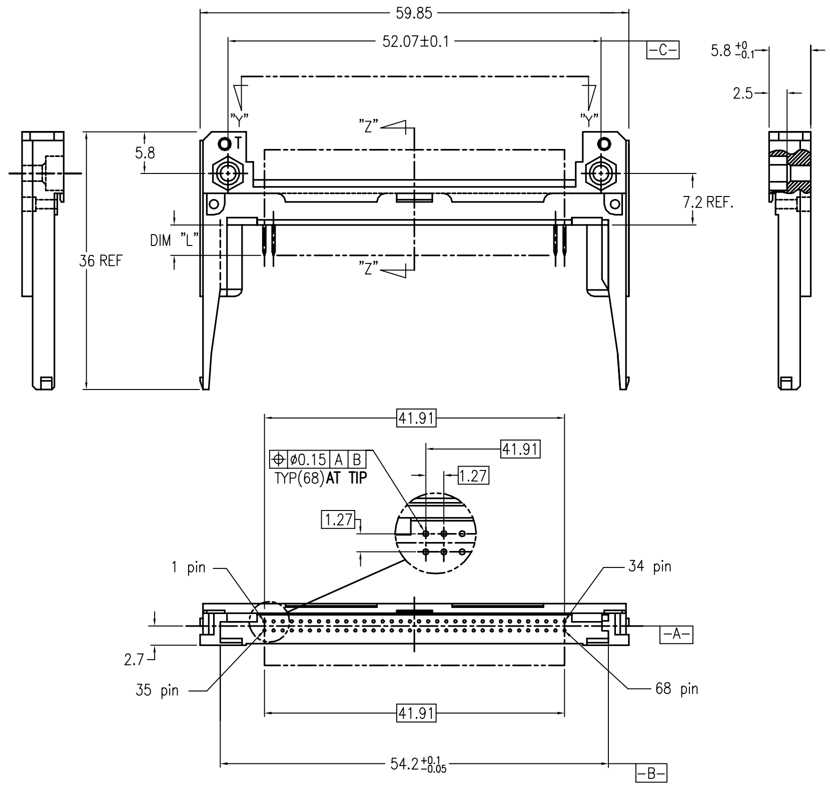
mat'l. code				surface ISO 1302	tolerance ISO 406 ISO 1101	projection	product family PCMCIA
ltr	ecn no	dr	date	tolerances unless otherwise specified			title
J	N06-0065	M.Z	04/02'06	angles	0.X±0.3	MM	68 POS EJECTOR HEADER ASSY FOR LOW VOLTAGE
K	N07-0219	M.Z	12/07'07	linear	0.XX±0.13		
L	N08-0041	M.Z	03/10'08	±2°	0.XXX±0.05	scale 1:1	
M	N08-0219	M.Z	10/10'08	dr M.Hasegawa 2/24/'05			dwg no 94898 sheet 1 of 7 size A4
N	N09-0045	SH	05/25/09	engr M.Hasegawa 2/24/'05			
P	ELX-N-007954	ZK	11/01/11	chr			type CUSTOMER Drawing
R	ELX-N-011436	ZK	04/23/12	appd			

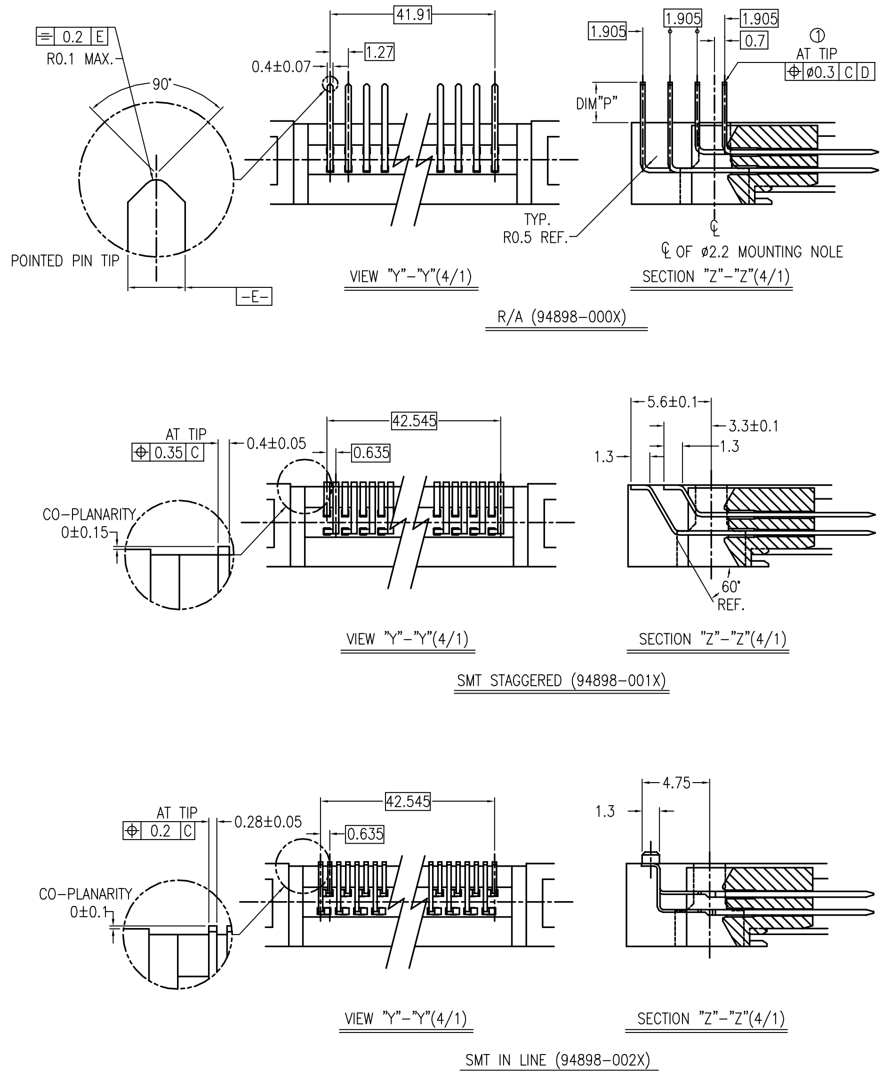
sheet	revision	R	R	R	R	R	R	R
index	sheet	1	2	3	4	5	6	7

form: A3

PDS: Rev :R STATUS: Released Printed: Apr 28, 2012

PRODUCT NO.
94898-000
94898-000LF
94898-000H
94898-000HLF
94898-000MLF
94898-001
94898-001LF
94898-001H
94898-001HLF
94898-002
94898-002LF
94898-002H
94898-002HLF





NOTES

① TRUE POSITION IS A FREE GRID TO PIN PATTERN ITSELF.
2. SEE TA-946 FOR PCB LAYOUT.
③ MATERIAL
HOUSING : HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
PIN : COPPER ALLOY.
HOLD-DOWN : BRASS
④ FINISH
PIN
UNDER PLATING : 0.5um MIN. Ni.
CONTACT AREA : 0.076 μm MIN. GOLD

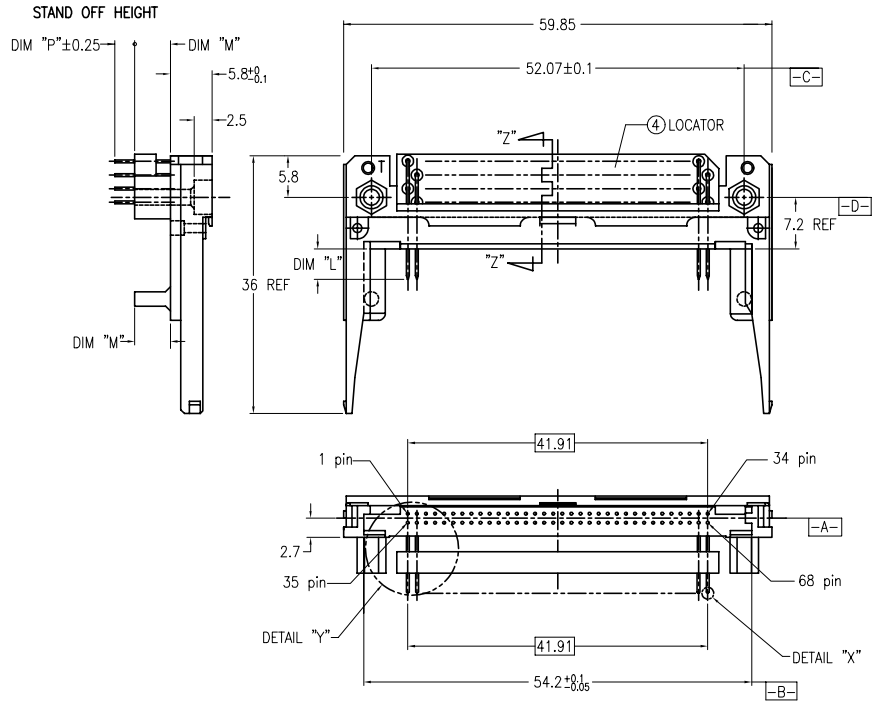
SOLDER AREA : 2.5um MIN. Sn-Pb.
OR 2.5um MIN. PURE Sn.(FOR -XXXLF)
HOLD-DOWN : 2.5um MIN. PURE Sn.
5. RECOMMENDED PCB HOLE (OPTIONAL HOLD-DOWN) : 2.3±0.1
6. SEQUENCE PIN ASSIGNMENT

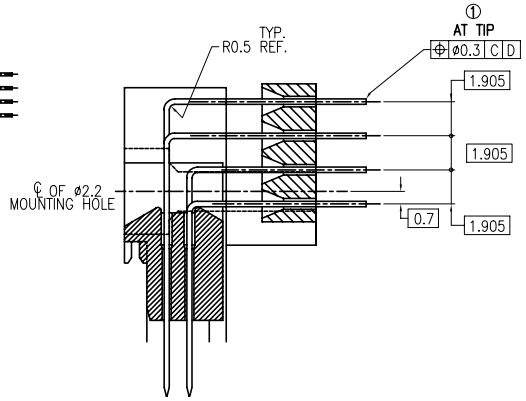
	DIM "L"		
	4.25±0.1	3.5±0.1	5.0±0.1
PIN No.	OTHERS	36.67	1,17,34 35,51,68

7. GENERAL TOLERANCE : ±0.3
8. SEE SHEET 1 REGARDING COMPONENTS.
9. IF LEAD FREE P/N,THE HOUSING WILL WITHSTAND EXPOSURE TO 260° C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
10. LEAD FREE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DISCRIBLED IN GS-22-008
11. IF LEAD FREE P/N, PACKAGE MEETS GS-14-920 SPECIFICATION

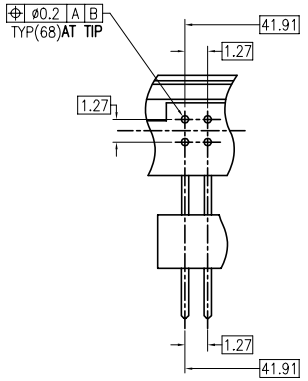
mat'l. code	surface ISO 1302	tolerance ISO 406 ISO 1101	projection	product family PCMCIA
ltr / ecn no / dr / date	tolerances unless otherwise specified			title
R	angles ±2°	linear 0.X±0.3 / 0.XX±0.13 / 0.XXX±0.05	MM	68 POS EJECTOR HEADER ASSY FOR LOW VOLTAGE
			scale 1:1	
	dr M.Hasegawa 2/24/'05			dwg no 94898 / sheet2of7 / size A4
	engr M.Hasegawa 2/24/'05			
	chr			
	appd			type CUSTOMER Drawing
sheet index	revision sheet			

PRODUCT NO.
94898-010
94898-010LF
94898-020/020M
94898-020LF/020MLF
94898-021MLF
94898-040
94898-040LF/040MLF

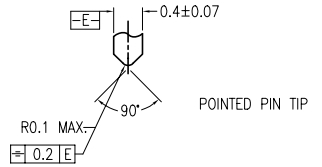




SECTION "Z"–"Z" (5/1)



DETAIL "Y" (5/1)



DETAIL "X" (20/1)
TYP(68)

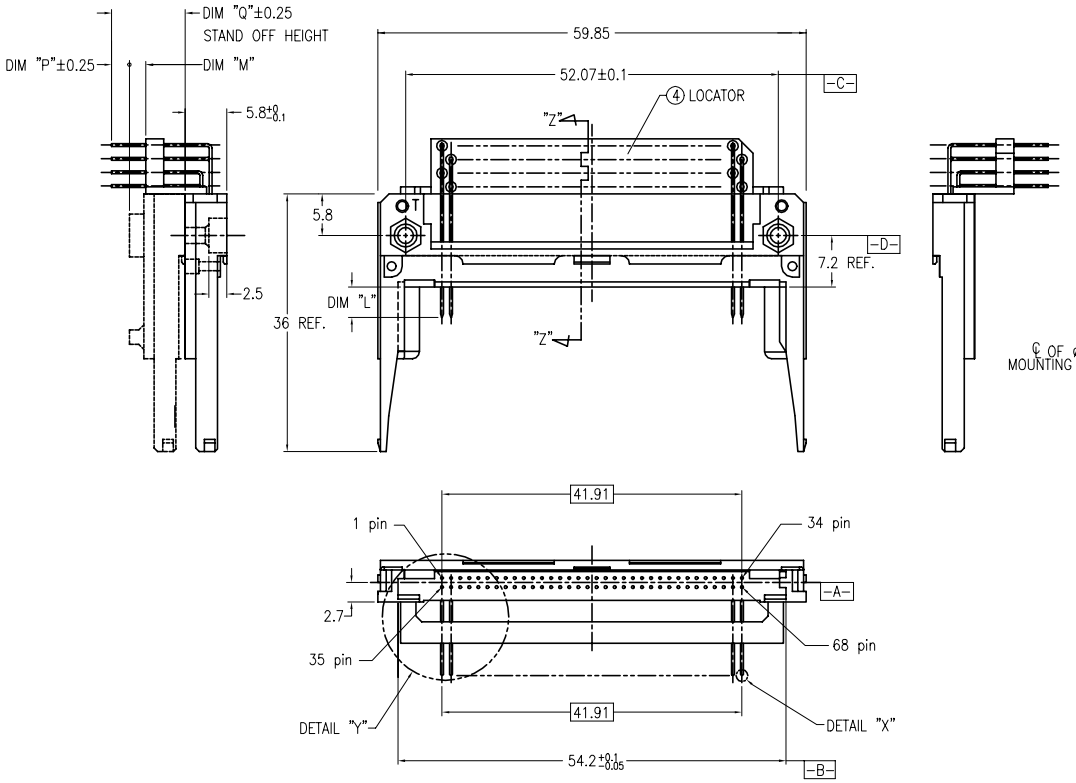
① TRUE POSITION IS A FREE GRID TO PIN PATTERN ITSELF.
2. SEE TA-946 FOR PCB LAYOUT.
③ MATERIAL
HOUSING : HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
PIN : COPPER ALLOY.
HOLD-DOWN : BRASS
④ FINISH
PIN
UNDER PLATING : 0.5um MIN. Ni.
CONTACT AREA : 0.076 µm MIN. GOLD
SOLDER AREA : 2.5um MIN. Sn-Pb.
OR 2.5um MIN. PURE Sn.(FOR -XXXLF)
HOLD-DOWN : 2.5um MIN. PURE Sn.
5. RECOMMENDED PCB HOLE (OPTIONAL HOLD-DOWN) : 2.3±0.1
6. SEQUENCE PIN ASSIGNMENT

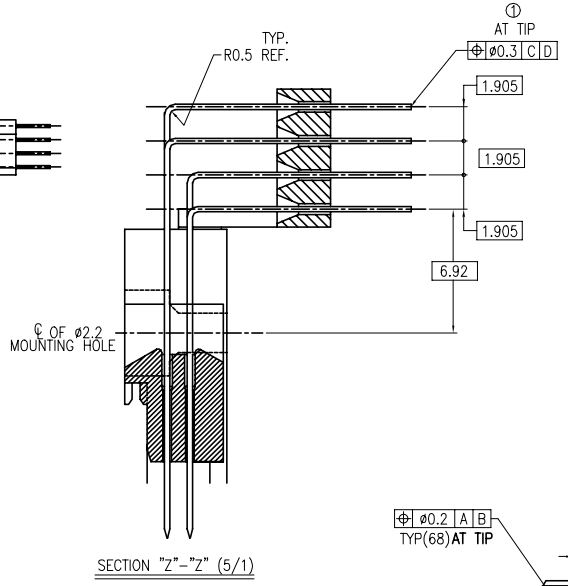
	DIM "L"		
	4.25±0.1	3.5±0.1	5.0±0.1
PIN No.	OTHERS	36.67	1,17,34 / 35,51,68

7. GENERAL TOLERANCE : ±0.3
8. SEE SHEET 1 REGARDING COMPONENTS.
9. IF LEAD FREE P/N,THE HOUSING WILL WITHSTAND EXPOSURE TO 260° C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
10. LEAD FREE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DISCRIBLED IN GS-22-008
11. IF LEAD FREE P/N, PACKAGE MEETS GS-14-920 SPECIFICATION
12 "M" SHOWS IT IS LOW COST VERSION,IT IS OPTIONAL AND IN FIRST OF LETTER OF PART NO., SUCH AS 94898-020MLF IS LOW COST VERSION 94898-020LF IS NOT LOW COST VERSION.

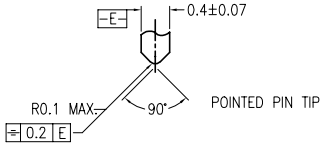
mat'l. code				surface ISO 1302	tolerance ISO 406 ISO 1101	projection	product family PCMCIA
ltr	ecn no	dr	date	tolerances unless otherwise specified			title
R				angles ±2°	linear 0.X±0.3 / 0.XX±0.13 / 0.XXX±0.05	MM	68 POS EJECTOR HEADER ASSY FOR LOW VOLTAGE
				dr M.Hasegawa 2/24/'05		scale 1:1	
				engr M.Hasegawa 2/24/'05			dwg no 94898 sheet 3 of 7 size A4
				chr			
				appd			type CUSTOMER Drawing
sheet index	revision sheet						

PRODUCT NO.
94898-005
94898-005LF
94898-045
94898-045LF

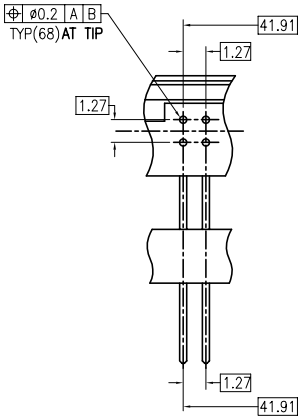




SECTION "Z"-"Z" (5/1)



DETAIL "X" (20/1)
TYP(68)



DETAIL "Y" (5/1)

NOTES

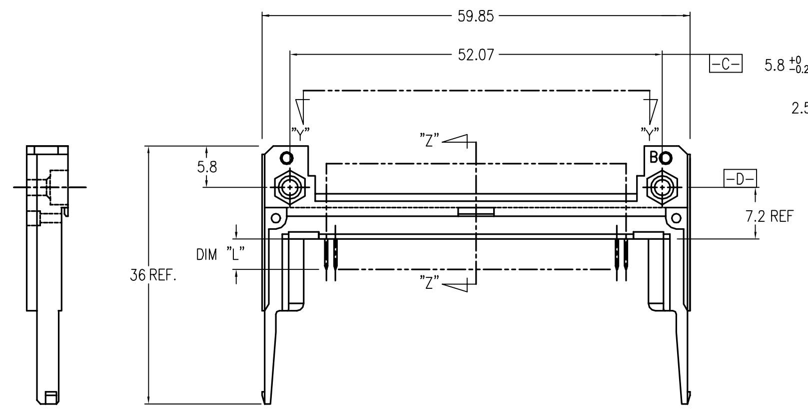
① TRUE POSITION IS A FREE GRID TO PIN PATTERN ITSELF.
2. SEE TA-946 FOR PCB LAYOUT.
③ MATERIAL
HOUSING : HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
PIN : COPPER ALLOY.
HOLD-DOWN : BRASS
④ FINISH
PIN
UNDER PLATING : 0.5um MIN. Ni.
CONTACT AREA : 0.076 µm MIN. GOLD
SOLDER AREA : 2.5um MIN. Sn-Pb.
OR 2.5um MIN. PURE Sn.(FOR -XXXLF)
HOLD-DOWN : 2.5um MIN. PURE Sn.
5. RECOMMENDED PCB HOLE (OPTIONAL HOLD-DOWN) : 2.3±0.1
6. SEQUENCE PIN ASSIGNMENT

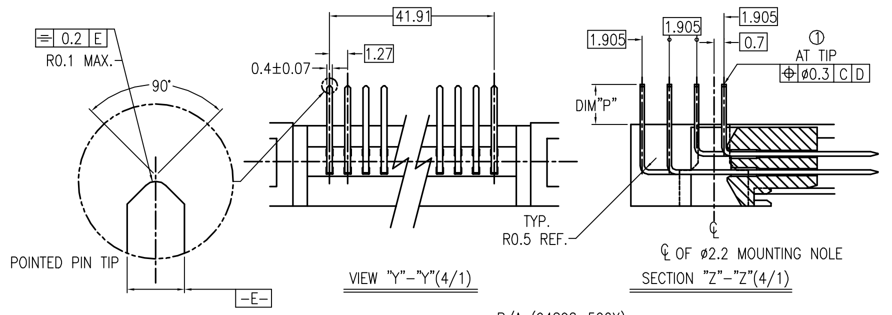
	DIM "L"		
	4.25±0.1	3.5±0.1	5.0±0.1
PIN No.	OTHERS	36.67	1,17,34 / 35,51,68

7. GENERAL TOLERANCE : ±0.3
8. SEE SHEET 1 REGARDING COMPONENTS.
9. IF LEAD FREE P/N,THE HOUSING WILL WITHSTAND EXPOSURE TO 260° C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
10. LEAD FREE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DISCRIBLED IN GS-22-008
11. IF LEAD FREE P/N, PACKAGE MEETS GS-14-920 SPECIFICATION

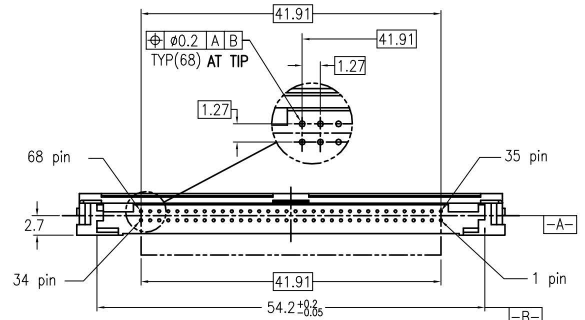
mat'l. code				surface	tolerance	projection	product family
				ISO 1302	ISO 406 ISO 1101		PCMCIA
ltr	ecn no	dr	date	tolerances unless otherwise specified			title
R				angles	linear 0.X±0.3	MM	68 POS EJECTOR HEADER ASSY FOR LOW VOLTAGE
					0.XX±0.13		
				±2°	0.XXX±0.05	scale 1:1	
				dr M.Hasegawa 2/24/'05			dwg no 94898 sheet 4 of 7 size A4
				engr M.Hasegawa 2/24/'05			
				chr			type CUSTOMER Drawing
				appd			
sheet index	revision sheet						

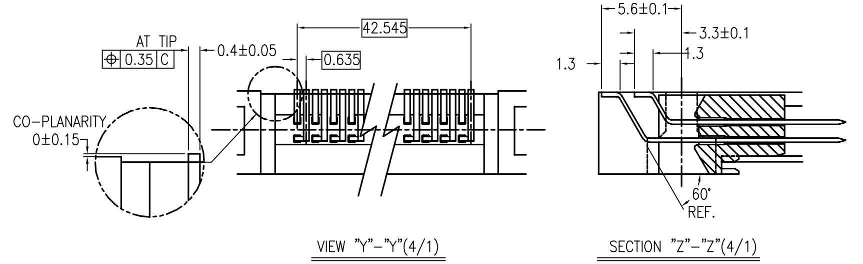
PRODUCT NO.
94898-500
94898-500LF
94898-500H
94898-500HLF
94898-501
94898-501LF
94898-501H
94898-501HLF
94898-502
94898-502J — SEE NOTE 12
94898-502LF
94898-502H
94898-502HLF



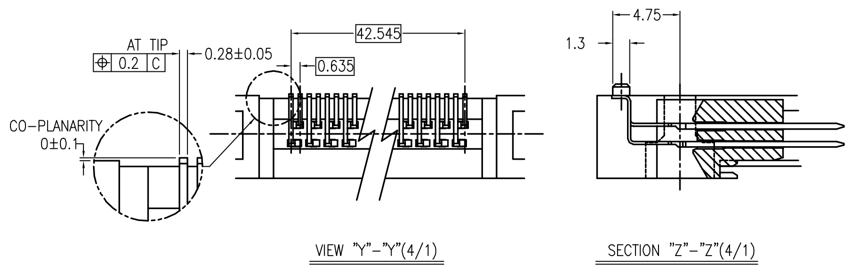


R/A (94898-500X)





SMT STAGGERED (94898-501X)



SMT IN LINE (94898-502X)

NOTES

1. (1) TRUE POSITION IS A FREE GRID TO PIN PATTERN ITSELF.
2. SEE TA-946 FOR PCB LAYOUT.
3. (3) MATERIAL
   - HOUSING : HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
   - PIN : COPPER ALLOY.
   - HOLD-DOWN : BRASS
4. (4) FINISH
   - PIN
     - UNDER PLATING : 0.5um MIN. Ni.
     - CONTACT AREA : 0.076 μm MIN. GOLD
     - SOLDER AREA : 2.5um MIN. Sn-Pb. OR 2.5um MIN. PURE Sn.(FOR -XXXLF)
   - HOLD-DOWN : 2.5um MIN. PURE Sn.
5. RECOMMENDED PCB HOLE (OPTIONAL HOLD-DOWN) : 2.3±0.1
6. SEQUENCE PIN ASSIGNMENT

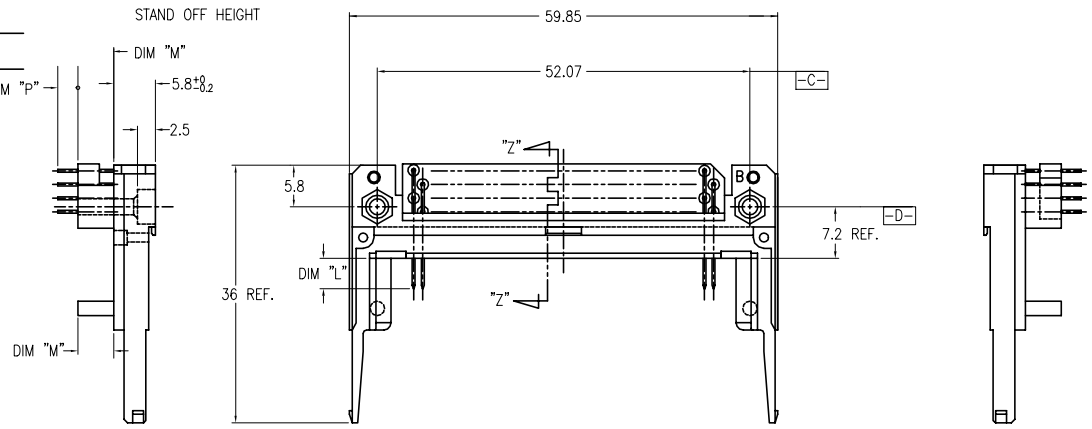
	DIM "L"		
	4.25±0.1	3.5±0.1	5.0±0.1
PIN No.	OTHERS	36.67	1,17,34 35,51,68

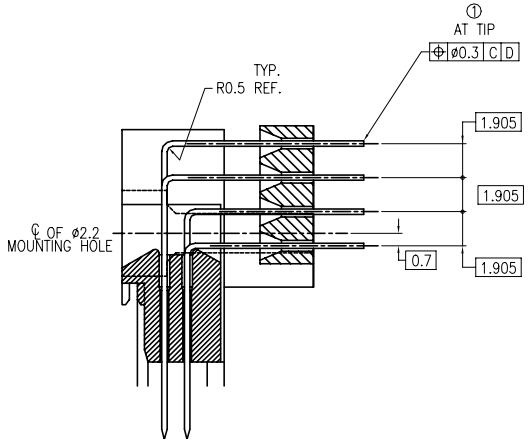
7. GENERAL TOLERANCE : ±0.3
8. SEE SHEET 1 REGARDING COMPONENTS.
9. IF LEAD FREE P/N,THE HOUSING WILL WITHSTAND EXPOSURE TO 260° C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
10. LEAD FREE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DISCRIBLED IN GS-22-008
11. IF LEAD FREE P/N, PACKAGE MEETS GS-14-920 SPECIFICATION
12. (12) THE P/N 94898-502J HAS SPECIAL TRAY, IT IS 10084720-001.

mat'l. code	surface	tolerance	projection	product family
	ISO 1302	ISO 406 ISO 1101		PCMCIA
ltr / ecn no / dr / date	tolerances unless otherwise specified			title
R	angles ±2°	linear 0.X±0.3, 0.XX±0.13, 0.XXX±0.05	MM, scale 1:1	68 POS EJECTOR HEADER ASSY FOR LOW VOLTAGE
	dr M.Hasegawa 2/24/'05		FCI	dwg no 94898, sheet 5 of 7, size A4
	engr M.Hasegawa 2/24/'05			
	chr			
	appd			type CUSTOMER Drawing
sheet index	revision sheet			

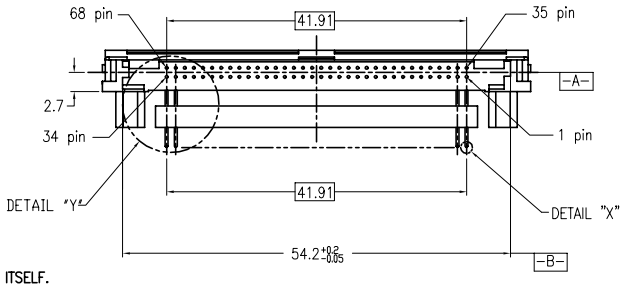
form: A3

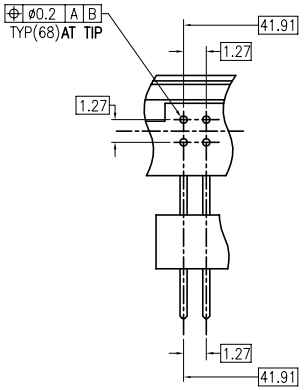
PRODUCT NO.	
94898-510	94898-510LF
94898-520	94898-520LF
94898-530	94898-530LF
94898-540	94898-540LF



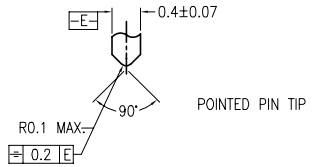


SECTION "Z"-"Z" (5/1)





DETAIL "Y" (5/1)



DETAIL "X" (20/1)
TYP(68)

NOTES

① TRUE POSITION IS A FREE GRID TO PIN PATTERN ITSELF.
2. SEE TA-946 FOR PCB LAYOUT.
③ MATERIAL
HOUSING : HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
PIN : COPPER ALLOY.
HOLD-DOWN : BRASS
④ FINISH
PIN
UNDER PLATING : 0.5μm MIN. Ni.
CONTACT AREA : 0.076 μm MIN. GOLD
SOLDER AREA : 2.5μm MIN. Sn-Pb.
OR 2.5μm MIN. PURE Sn.(FOR -XXXLF)
HOLD-DOWN : 2.5μm MIN. PURE Sn.
5. RECOMMENDED PCB HOLE (OPTIONAL HOLD-DOWN) : 2.3±0.1
6. SEQUENCE PIN ASSIGNMENT

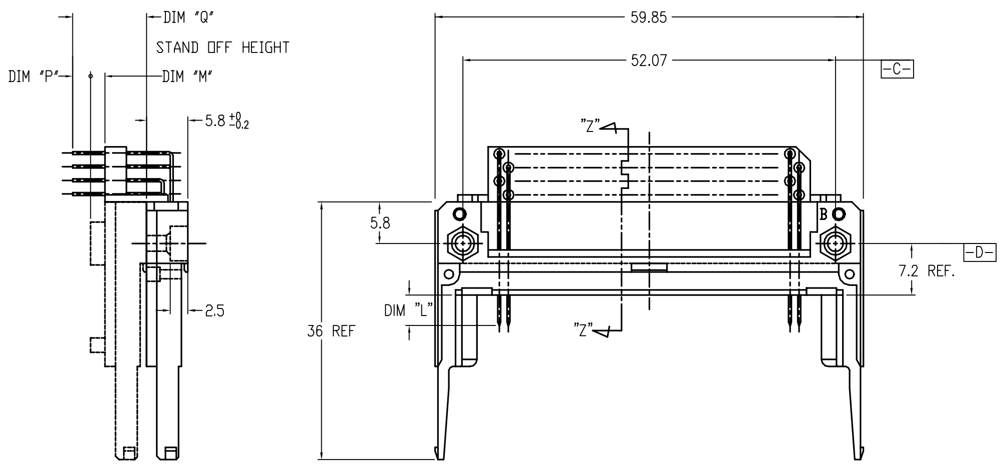
	DIM "L"		
	4.25±0.1	3.5±0.1	5.0±0.1
PIN No.	OTHERS	36.67	1,17,34 35,51,68

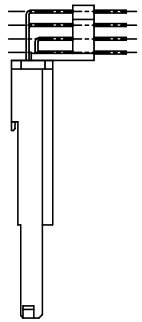
7. GENERAL TOLERANCE : ±0.3
8. SEE SHEET 1 REGARDING COMPONENTS.
9. IF LEAD FREE P/N,THE HOUSING WILL WITHSTAND EXPOSURE TO 260° C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
10. LEAD FREE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DISCRIBLED IN GS-22-008
11. IF LEAD FREE P/N, PACKAGE MEETS GS-14-920 SPECIFICATION

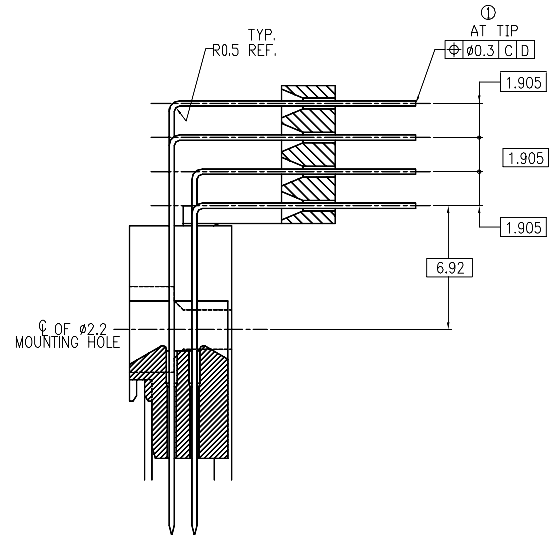
mat'l. code				surface	tolerance	projection	product family
				ISO 1302	ISO 406 ISO 1101		PCMCIA
ltr	ecn no	dr	date	tolerances unless otherwise specified			title
R				angles	0.X±0.3	MM	68 POS EJECTOR HEADER ASSY FOR LOW VOLTAGE
				linear	0.XX±0.13		
				±2°	0.XXX±0.05	scale 1:1	
				dr M.Hasegawa 2/24/'05			dwg no 94898 sheet 6 of 7 size A4
				engr M.Hasegawa 2/24/'05			
				chr			type CUSTOMER Drawing
				appd			
sheet index	revision sheet						

FCI CONFIDENTIAL

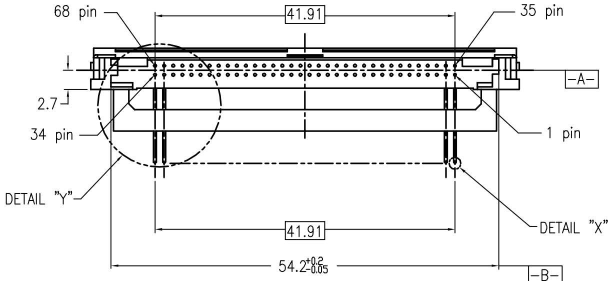
PRODUCT NO.
94898-505
94898-505LF
94898-535
94898-535LF
94898-545
94898-545LF

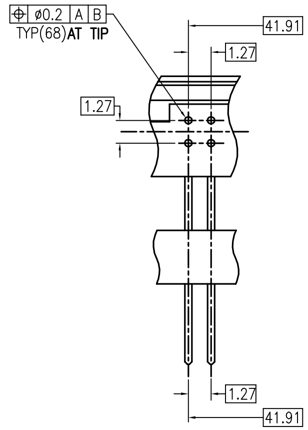




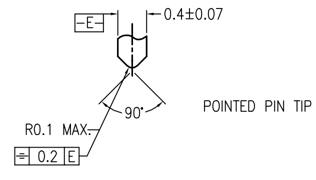


SECTION "Z"-"Z" (5/1)





DETAIL "Y" (5/1)



DETAIL "X" (20/1)
TYP(68)

NOTES
① TRUE POSITION IS A FREE GRID TO PIN PATTERN ITSELF.
2. SEE TA-946 FOR PCB LAYOUT.
③ MATERIAL
HOUSING : HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
PIN : COPPER ALLOY.
HOLD-DOWN : BRASS
④ FINISH
PIN
UNDER PLATING : 0.5um MIN. Ni.
CONTACT AREA : 0.076 μm MIN. GOLD

SOLDER AREA : 2.5um MIN. Sn-Pb.
OR 2.5um MIN. PURE Sn.(FOR -XXXLF)
HOLD-DOWN : 2.5um MIN. PURE Sn.
5. RECOMMENDED PCB HOLE (OPTIONAL HOLD-DOWN) : 2.3±0.1
6. SEQUENCE PIN ASSIGNMENT

PIN No. \ DIM "L"	4.25±0.1	3.5±0.1	5.0±0.1
	OTHERS	36.67	1,17,34 35,51,68

7. GENERAL TOLERANCE : ±0.3
8. SEE SHEET 1 REGARDING COMPONENTS.
9. IF LEAD FREE P/N,THE HOUSING WILL WITHSTAND EXPOSURE TO 260° C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
10. LEAD FREE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DISCRIBLED IN GS-22-008
11. IF LEAD FREE P/N, PACKAGE MEETS GS-14-920 SPECIFICATION

mat'l. code	
surface	ISO 1302
tolerance	ISO 406 ISO 1101
projection	
product family	PCMCIA
ltr / ecn no / dr / date	R
tolerances unless otherwise specified	angles ±2°; linear 0.X±0.3, 0.XX±0.13, 0.XXX±0.05
	MM
scale	1:1
title	68 POS EJECTOR HEADER ASSY FOR LOW VOLTAGE
dr	M.Hasegawa 2/24/'05
engr	M.Hasegawa 2/24/'05
chr	
appd	
dwg no	94898
sheet	7 of 7
size	A4
type	CUSTOMER Drawing
sheet index	revision sheet